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April 1st, 2010
Renesas Electronics Corporation

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72M-BIT DDR II+ SRAM
2.0 & 2.5 CLOCK CYCLES READ LATENCY
2-WORD BURST OPERATION

Description

The μPD44646092A-A and μPD44646093A-A are 8,388,608-word by 9-bit, the μPD44646182A-A and μPD44646183A-A are 4,194,304-word by 18-bit and the μPD44646362A-A and μPD44646363A-A are 2,097,152-word by 36-bit synchronous double data rate static RAM fabricated with advanced CMOS technology using full CMOS six-transistor memory cell.

The μPD44646xx2A-A is for 2.0 clock cycles and the μPD44646xx3A-A is for 2.5 clock cycles read latency. The μPD44646092A-A, μPD44646093A-A, μPD44646182A-A, μPD44646183A-A, μPD44646362A-A and μPD44646363A-A integrate unique synchronous peripheral circuitry and a burst counter. All input registers controlled by an input clock pair (K and K#) are latched on the positive edge of K and K#.

These products are suitable for application which require synchronous operation, high speed, low voltage, high density and wide bit configuration.

These products are packaged in 165-pin PLASTIC BGA.

Features

- 1.8 ± 0.1 V power supply
- 165-pin PLASTIC BGA (15 x 17)
- HSTL interface
- DLL/PLL circuitry for wide output data valid window and future frequency scaling
- Pipelined double data rate operation
- Common data input/output bus
- Two-tick burst for low DDR transaction size
- Two input clocks (K and K#) for precise DDR timing at clock rising edges only
- Two Echo clocks (CQ and CQ#)
- Data Valid pin (QVLD) supported
- Read latency : 2.0 & 2.5 clock cycles (Not selectable by user)
- Internally self-timed write control
- Clock-stop capability. Normal operation is restored in 20 μs after clock is resumed.
- User programmable impedance output (35 to 70 Ω)
- Fast clock cycle time : 2.5 ns (400 MHz) for 2.0 clock cycles read latency,
  2.0 ns (500 MHz) for 2.5 clock cycles read latency
- Simple control logic for easy depth expansion
- JTAG 1149.1 compatible test access port
- On-Die Termination (ODT) for better signal quality (Selectable ON/OFF by user)

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Ordering Information

2.0 Clock Cycles Read Latency

Part number	Cycle Time ns	Clock Frequency MHz	Organization (word x bit)	Core Supply Voltage V	I/O Interface	Package
μPD44646092AF5-E25-FQ1-A Note	2.5	400	8M x 9	1.8 ± 0.1	HSTL	165-pin PLASTIC BGA (15 x 17) Lead-free
μPD44646092AF5-E30-FQ1-A	3.0	333				
μPD44646092AF5-E33-FQ1-A	3.3	300				
μPD44646182AF5-E25-FQ1-A Note	2.5	400	4M x 18			
μPD44646182AF5-E30-FQ1-A	3.0	333				
μPD44646182AF5-E33-FQ1-A	3.3	300				
μPD44646362AF5-E25-FQ1-A Note	2.5	400	2M x 36			
μPD44646362AF5-E30-FQ1-A	3.0	333				
μPD44646362AF5-E33-FQ1-A	3.3	300				

Note Please contact our sales.

2.5 Clock Cycles Read Latency

Part number	Cycle Time ns	Clock Frequency MHz	Organization (word x bit)	Core Supply Voltage V	I/O Interface	Package
μPD44646093AF5-E20-FQ1-A Note	2.0	500	8M x 9	1.8 ± 0.1	HSTL	165-pin PLASTIC BGA (15 x 17) Lead-free
μPD44646093AF5-E22-FQ1-A	2.2	450				
μPD44646093AF5-E25-FQ1-A	2.5	400				
μPD44646093AF5-E30-FQ1-A	3.0	333				
μPD44646183AF5-E20-FQ1-A Note	2.0	500	4M x 18			
μPD44646183AF5-E22-FQ1-A	2.2	450				
μPD44646183AF5-E25-FQ1-A	2.5	400				
μPD44646183AF5-E30-FQ1-A	3.0	333				
μPD44646363AF5-E20-FQ1-A Note	2.0	500	2M x 36			
μPD44646363AF5-E22-FQ1-A	2.2	450				
μPD44646363AF5-E25-FQ1-A	2.5	400				
μPD44646363AF5-E30-FQ1-A	3.0	333				

Note Please contact our sales.

Feature Differences between DDR II and DDR II+

Features	DDR II	DDR II+	Note
Frequency (DLL/PLL ON)	200 MHz to 333 MHz	300 MHz to 500 MHz	
Organization	x9 / x18 / x36	x9 / x18 / x36	
V_{DD}	1.8 ± 0.1 V	1.8 ± 0.1 V	
$V_{DD}Q$	1.8 ± 0.1 V or 1.5 ± 0.1 V	1.8 ± 0.1 V or 1.5 ± 0.1 V	
Read Latency	1.5 clock cycles	2.0 & 2.5 clock cycles	1
Write Latency	1.0 clock cycle	1.0 clock cycle	2
Input Clocks (K, K#)	Single Ended (K, K#)	Single Ended (K, K#)	
Output Clocks (C, C#)	Yes	No	
Echo Clock Number (CQ, CQ#)	1 Pair	1 Pair	3
Package	165-pin PLASTIC BGA (15 x 17)	165-pin PLASTIC BGA (15 x 17)	
Fixed Burst Address for DDR CIO; A0 for burst 2	Yes	No	4
QVLD	No	Yes	5
ODT	No	Yes	6

Notes 1. DDR II+ read latency is not user selectable. Offered as two different devices. 2.5 clock cycle is consortium standard, and 2.0 clock cycle is vendor option.

2. DDR II+ write latency is 1.0 clock cycle regardless of read latency.

3. Echo Clocks are single-ended outputs.

4. Linear burst is not supported at DDR II + CIO.

5. Edge aligned with Echo Clocks.

6. ODT ON/OFF is user selectable.

Pin Configurations

165-pin PLASTIC BGA (15 x 17)

(Top View)

[μPD44646092A-A], [μPD44646093A-A]

8M x 9

	1	2	3	4	5	6	7	8	9	10	11
A	CQ#	A	A	R, W#	NC	K#	NC/144M	LD#	A	A	CQ
B	NC	NC	NC	A	NC/288M	K	BW0#	A	NC	NC	DQ4
C	NC	NC	NC	V_{SS}	A	A	A	V_{SS}	NC	NC	NC
D	NC	NC	NC	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	NC	NC	NC
E	NC	NC	DQ5	$V_{DD}Q$	V_{SS}	V_{SS}	V_{SS}	$V_{DD}Q$	NC	NC	DQ3
F	NC	NC	NC	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	NC
G	NC	NC	DQ6	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	NC
H	DLL#	V_{REF}	$V_{DD}Q$	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	$V_{DD}Q$	V_{REF}	ZQ
J	NC	NC	NC	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	DQ2	NC
K	NC	NC	NC	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	NC
L	NC	DQ7	NC	$V_{DD}Q$	V_{SS}	V_{SS}	V_{SS}	$V_{DD}Q$	NC	NC	DQ1
M	NC	NC	NC	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	NC	NC	NC
N	NC	NC	NC	V_{SS}	A	A	A	V_{SS}	NC	NC	NC
P	NC	NC	DQ8	A	A	QVLD	A	A	NC	NC	DQ0
R	TDO	TCK	A	A	A	ODT	A	A	A	TMS	TDI

A	: Address inputs	TMS	: IEEE 1149.1 Test input
DQ0 to DQ8	: Data inputs / outputs	TDI	: IEEE 1149.1 Test input
LD#	: Synchronous load	TCK	: IEEE 1149.1 Clock input
R, W#	: Read Write input	TDO	: IEEE 1149.1 Test output
BW0#	: Byte Write data select	V_{REF}	: HSTL input reference input
K, K#	: Input clock	V_{DD}	: Power Supply
CQ, CQ#	: Echo clock	$V_{DD}Q$	: Power Supply
ZQ	: Output impedance matching	V_{SS}	: Ground
DLL#	: DLL/PLL disable	NC	: No connection
QVLD	: Q Valid output	NC/xxM	: Expansion address for xxMb
ODT	: ODT Control Input		

Remarks 1. ×××# indicates active LOW signal.

2. Refer to **Package Drawing** for the index mark.

3. 7A and 5B are expansion addresses: 7A for 144Mb

: 7A and 5B for 288Mb

165-pin PLASTIC BGA (15 x 17)

(Top View)

[μPD44646182A-A], [μPD44646183A-A]

4M x 18

	1	2	3	4	5	6	7	8	9	10	11
A	CQ#	A	A	R, W#	BW1#	K#	NC/144M	LD#	A	A	CQ
B	NC	DQ9	NC	A	NC/288M	K	BW0#	A	NC	NC	DQ8
C	NC	NC	NC	V_{SS}	A	NC	A	V_{SS}	NC	DQ7	NC
D	NC	NC	DQ10	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	NC	NC	NC
E	NC	NC	DQ11	$V_{DD}Q$	V_{SS}	V_{SS}	V_{SS}	$V_{DD}Q$	NC	NC	DQ6
F	NC	DQ12	NC	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	DQ5
G	NC	NC	DQ13	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	NC
H	DLL#	V_{REF}	$V_{DD}Q$	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	$V_{DD}Q$	V_{REF}	ZQ
J	NC	NC	NC	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	DQ4	NC
K	NC	NC	DQ14	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	DQ3
L	NC	DQ15	NC	$V_{DD}Q$	V_{SS}	V_{SS}	V_{SS}	$V_{DD}Q$	NC	NC	DQ2
M	NC	NC	NC	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	NC	DQ1	NC
N	NC	NC	DQ16	V_{SS}	A	A	A	V_{SS}	NC	NC	NC
P	NC	NC	DQ17	A	A	QVLD	A	A	NC	NC	DQ0
R	TDO	TCK	A	A	A	ODT	A	A	A	TMS	TDI

A	: Address inputs	TMS	: IEEE 1149.1 Test input
DQ0 to DQ17	: Data inputs / outputs	TDI	: IEEE 1149.1 Test input
LD#	: Synchronous load	TCK	: IEEE 1149.1 Clock input
R, W#	: Read Write input	TDO	: IEEE 1149.1 Test output
BW0#, BW1#	: Byte Write data select	V_{REF}	: HSTL input reference input
K, K#	: Input clock	V_{DD}	: Power Supply
CQ, CQ#	: Echo clock	$V_{DD}Q$	: Power Supply
ZQ	: Output impedance matching	V_{SS}	: Ground
DLL#	: DLL/PLL disable	NC	: No connection
QVLD	: Q Valid output	NC/xxM	: Expansion address for xxMb
ODT	: ODT Control Input		

Remarks 1. ×××# indicates active LOW signal.

2. Refer to **Package Drawing** for the index mark.

3. 7A and 5B are expansion addresses: 7A for 144Mb

: 7A and 5B for 288Mb

165-pin PLASTIC BGA (15 x 17)

(Top View)

[μPD44646362A-A], [μPD44646363A-A]

2M x 36

	1	2	3	4	5	6	7	8	9	10	11
A	CQ#	NC/144M	A	R, W#	BW2#	K#	BW1#	LD#	A	A	CQ
B	NC	DQ27	DQ18	A	BW3#	K	BW0#	A	NC	NC	DQ8
C	NC	NC	DQ28	V_{SS}	A	NC	A	V_{SS}	NC	DQ17	DQ7
D	NC	DQ29	DQ19	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	NC	NC	DQ16
E	NC	NC	DQ20	$V_{DD}Q$	V_{SS}	V_{SS}	V_{SS}	$V_{DD}Q$	NC	DQ15	DQ6
F	NC	DQ30	DQ21	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	DQ5
G	NC	DQ31	DQ22	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	DQ14
H	DLL#	V_{REF}	$V_{DD}Q$	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	$V_{DD}Q$	V_{REF}	ZQ
J	NC	NC	DQ32	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	DQ13	DQ4
K	NC	NC	DQ23	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	DQ12	DQ3
L	NC	DQ33	DQ24	$V_{DD}Q$	V_{SS}	V_{SS}	V_{SS}	$V_{DD}Q$	NC	NC	DQ2
M	NC	NC	DQ34	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	NC	DQ11	DQ1
N	NC	DQ35	DQ25	V_{SS}	A	A	A	V_{SS}	NC	NC	DQ10
P	NC	NC	DQ26	A	A	QVLD	A	A	NC	DQ9	DQ0
R	TDO	TCK	A	A	A	ODT	A	A	A	TMS	TDI

A	: Address inputs	TMS	: IEEE 1149.1 Test input
DQ0 to DQ35	: Data inputs / outputs	TDI	: IEEE 1149.1 Test input
LD#	: Synchronous load	TCK	: IEEE 1149.1 Clock input
R, W#	: Read Write input	TDO	: IEEE 1149.1 Test output
BW0# to BW3#	: Byte Write data select	V_{REF}	: HSTL input reference input
K, K#	: Input clock	V_{DD}	: Power Supply
CQ, CQ#	: Echo clock	$V_{DD}Q$	: Power Supply
ZQ	: Output impedance matching	V_{SS}	: Ground
DLL#	: DLL/PLL disable	NC	: No connection
QVLD	: Q Valid output	NC/xxM	: Expansion address for xxMb
ODT	: ODT Control Input		

Remarks 1. ×××# indicates active LOW signal.

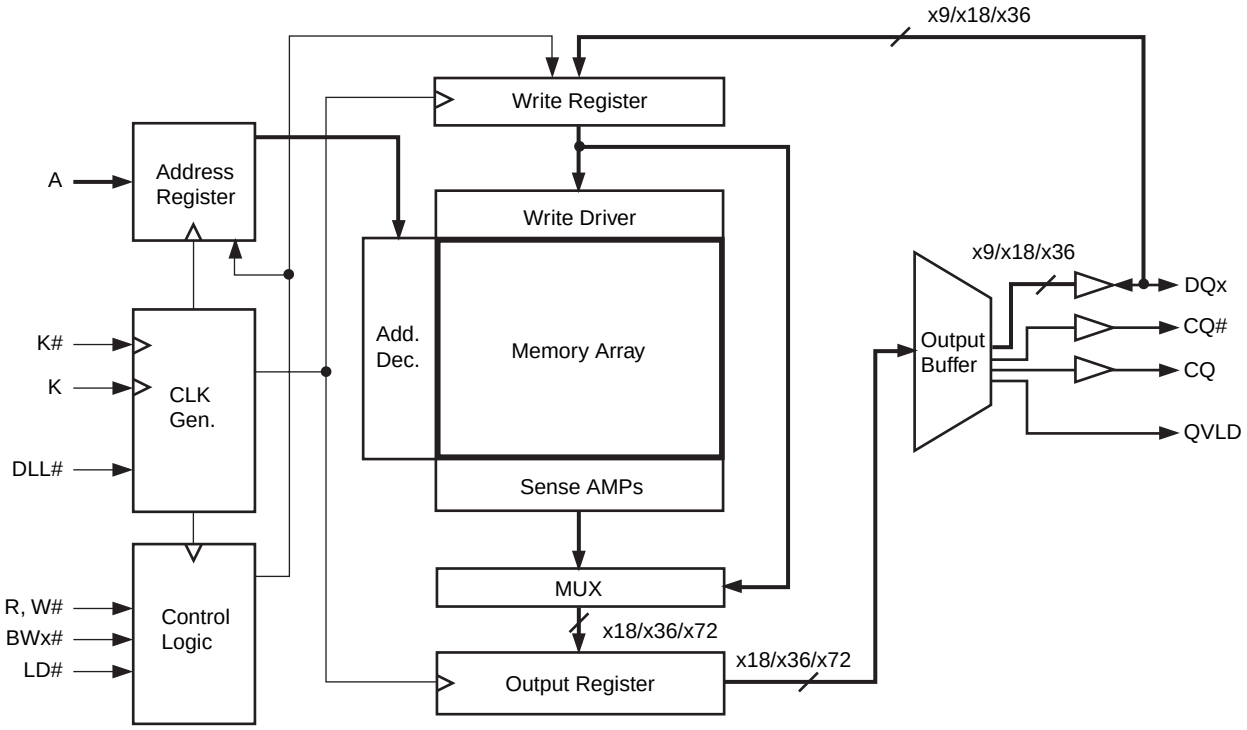
2. Refer to **Package Drawing** for the index mark.

3. 2A is expansion address for 144Mb.

Pin Identification

Symbol	Type	Description
A	Input	Synchronous Address Inputs: These inputs are registered and must meet the setup and hold times around the rising edge of K. All transactions operate on a burst of two words (one clock period of bus activity). These inputs are ignored when device is deselected, i.e., NOP (LD# = HIGH).
DQ0 to DQxx	Input/Output	Synchronous Data IOs: Input data must meet setup and hold times around the rising edges of K and K#. Output data is synchronized to the respective K and K#. x9 device uses DQ0 to DQ8. x18 device uses DQ0 to DQ17. x36 device uses DQ0 to DQ35.
LD#	Input	Synchronous Load: This input is brought LOW when a bus cycle sequence is to be defined. This definition includes address and read/write direction. All transactions operate on a burst of 2 data (one clock period of bus activity).
R, W#	Input	Synchronous Read/Write Input: When LD# is LOW, this input designates the access type (READ when R, W# is HIGH, WRITE when R, W# is LOW) for the loaded address. R, W# must meet the setup and hold times around the rising edge of K.
BWx#	Input	Synchronous Byte Writes: When LOW these inputs cause their respective byte to be registered and written during WRITE cycles. These signals must meet setup and hold times around the rising edges of K and K# for each of the two rising edges comprising the WRITE cycle. See **Pin Configurations** for signal to data relationships. x9 device uses BW0#. x18 device uses BW0#, BW1#. x36 device uses BW0# to BW3#. See **Byte Write Operation** for relation between BWx# and DQxx.
K, K#	Input	Input Clock: This input clock pair registers address and control inputs on the rising edge of K, and registers data on the rising edge of K and the rising edge of K#. K# is ideally 180 degrees out of phase with K. All synchronous inputs must meet setup and hold times around the clock rising edges.
CQ, CQ#	Output	Synchronous Echo Clock Outputs. The rising edges of these outputs are tightly matched to the synchronous data outputs and can be used as a data valid indication. These signals run freely and do not stop when DQ tristates. If K and K# are stopped in the single clock mode, CQ and CQ# will also stop.
ZQ	Input	Output Impedance Matching Input: This input is used to tune the device outputs to the system data bus impedance. DQ, CQ, CQ# and QVLD output impedance are set to 0.2 x RQ, where RQ is a resistor from this bump to ground. The output impedance can be minimized by directly connect ZQ to $V_{DD}Q$. This pin cannot be connected directly to GND or left unconnected. The output impedance is adjusted every 20 μs upon power-up to account for drifts in supply voltage and temperature. After replacement for a resistor, the new output impedance is reset by implementing power-on sequence.
DLL#	Input	DLL/PLL Disable: When DLL# is LOW, the operation can be performed at a clock frequency slower than TKHKH (MAX.) without the DLL/PLL circuit being used. The AC/DC characteristics cannot be guaranteed. For normal operation, DLL# must be HIGH and it can be connected to $V_{DD}Q$ through a 10 kΩ or less resistor.
QVLD	Output	Q valid Output: The Q Valid indicates valid output data. QVLD is edge aligned with CQ and CQ#.
ODT	Input	ODT Control Input: When the ODT control pin is HIGH, the ODT function is turned on at DQxx and BWx# pins. The ODT resistors are set to 0.6 x RQ, where RQ is a resistor from ZQ pin bump to ground. When the ODT Control pin is LOW or No Connect, the ODT function is turned off. The ODT ON/OFF is set at power-on sequence. The ODT can not change the state after power-on. To enable ODT function, ODT pin must be HIGH and it can be connected to $V_{DD}Q$ through a 10 kΩ or less resistor.
TMS TDI	Input	IEEE 1149.1 Test Inputs: 1.8 V I/O level. These balls may be left Not Connected if the JTAG function is not used in the circuit.
TCK	Input	IEEE 1149.1 Clock Input: 1.8 V I/O level. This pin must be tied to V_{SS} if the JTAG function is not used in the circuit.
TDO	Output	IEEE 1149.1 Test Output: 1.8 V I/O level. When providing any external voltage to TDO signal, it is recommended to pull up to V_{DD}.
V_{REF}	–	HSTL Input Reference Voltage: Nominally $V_{DD}Q/2$. Provides a reference voltage for the input buffers.
V_{DD}	Supply	Power Supply: 1.8 V nominal. See **Recommended DC Operating Conditions** and **DC Characteristics** for range.
$V_{DD}Q$	Supply	Power Supply: Isolated Output Buffer Supply. Nominally 1.5 V. 1.8 V is also permissible. See **Recommended DC Operating Conditions** and **DC Characteristics** for range.
V_{SS}	Supply	Power Supply: Ground
NC	–	No Connect: These signals are not connected internally.

Block Diagram



Power-On Sequence in DDR II+ SRAM

DDR II+ SRAMs must be powered up and initialized in a predefined manner to prevent undefined operations. The following timing charts show the recommended power-on sequence.

The following power-up supply voltage application is recommended: V_{SS}, V_{DD}, $V_{DD}Q$, V_{REF}, then V_{IN}. V_{DD} and $V_{DD}Q$ can be applied simultaneously, as long as $V_{DD}Q$ does not exceed V_{DD} by more than 0.5 V during power-up. The following power-down supply voltage removal sequence is recommended: V_{IN}, V_{REF}, $V_{DD}Q$, V_{DD}, V_{SS}. V_{DD} and $V_{DD}Q$ can be removed simultaneously, as long as $V_{DD}Q$ does not exceed V_{DD} by more than 0.5 V during power-down.

Power-On Sequence

Apply power and tie DLL# to HIGH.

- Apply V_{DD} before $V_{DD}Q$.
- Apply $V_{DD}Q$ before V_{REF} or at the same time as V_{REF}.

Select ODT ON/OFF.

Provide stable clock for more than 20 μs to lock the DLL/PLL.

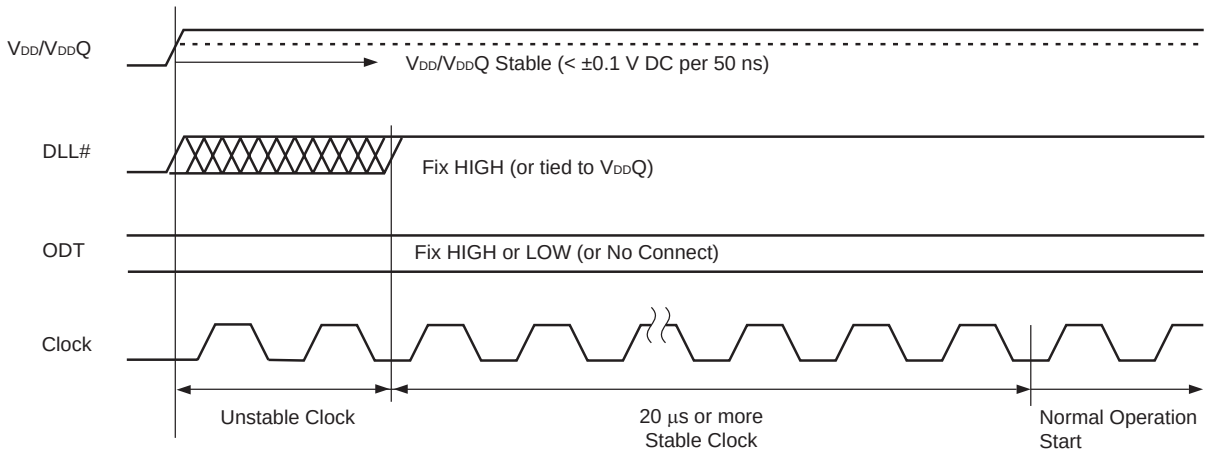
DLL/PLL Constraints

The DLL/PLL uses K clock as its synchronizing input and the input should have low phase jitter which is specified as TKC var. The DLL/PLL can cover 190 MHz as the lowest frequency. If the input clock is unstable and the DLL/PLL is enabled, then the DLL/PLL may lock onto an undesired clock frequency.

ODT initialization

The ODT ON/OFF is set at power-on sequence. When the ODT Control pin is HIGH before applying stable clock, the ODT function is turn on. When the ODT Control pin is LOW or No Connect, the ODT function is off. The ODT can not change the state after power-on.

Power-On Waveforms



On-Die Termination (ODT)

On-Die Termination (ODT) is enabled by setting ODT control pin to HIGH at power-on sequence. The ODT resistors (R_{TT}) are set to 0.6 x RQ, where RQ is a resistor from ZQ pin bump to ground. With ODT on, all the DQs and BW#s are terminated to $V_{DD}Q$ and V_{SS} with a resistance R_{TT} x 2. The command, address, and clock signals are not terminated. Figure below shows the equivalent circuit of a DQxx and BWx# receiver with ODT. ODT of DQs are dynamically switched off before a half cycle when READ commands starts and are designed to be off prior to the product driving the bus. ODT of BW#s are always on. Similarly, ODTs are designed to switch on after a half cycle when the product has issued the last piece of data.

When the ODT control pin is LOW or No Connect at power-on sequence, the ODT function is always off.

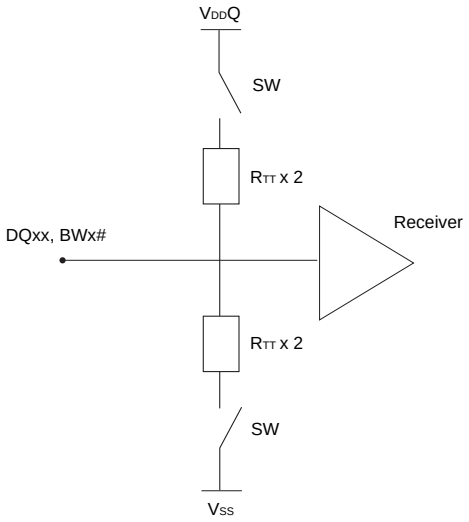
When the ODT be changed the state after power-on, the AC/DC characteristics cannot be guaranteed.

On-Die Termination DC Parameters

Description	Symbol	MIN.	TYP.	MAX.	Units
On-Die termination	R_{TT}	105	150	210	Ω
External matching resistor	RQ	175	250	350	Ω

Remark The allowable range of RQ to guarantee impedance matching a tolerance of ± 20 % is between 175 Ω and 350 Ω.

On- Die Termination-Equivalent Circuit



QDR™ Consortium specification for ODT is defined when 6R is HIGH and vendor specification when 6R is LOW or Floating. NEC specification is "Disabled" with 6R LOW or Floating as follows.

ODT-option clarification

6R input	ODT function		Termination value	
	Consortium specification	NEC specification	Consortium specification	NEC specification
HIGH	Active	Active	R_{TT} = 0.6 x RQ	R_{TT} = 0.6 x RQ
LOW	Vendor specification	Disabled	Vendor specification	–
Floating	Vendor specification	Disabled	Vendor specification	–

Note In case of nominal value (RQ = 250 Ω), R_{TT} = 150 Ω.

Truth Table

2.0 Clock Cycles Read Latency

[μPD44646092A-A], [μPD44646182A-A], [μPD44646362A-A]

Operation	CLK	LD#	R,W#	DQ			
WRITE cycle	L → H	L	L	Data in			
Load address, input write data on					Input data	D_A(A+0)	D_A(A+1)
consecutive K and K# rising edge					Input clock	K(t+1) ↑	K#(t+1) ↑
READ cycle	L → H	L	H	Data out			
Load address, read data on					Output data	Q_A(A+0)	Q_A(A+1)
consecutive K and K# rising edge					Output clock	K(t+2) ↑	K#(t+2) ↑
NOP (No operation)	L → H	H	X	DQ = High-Z			
Clock stop	Stopped	X	X	Previous state			

2.5 Clock Cycles Read Latency

[μPD44646093A-A], [μPD44646183A-A], [μPD44646363A-A]

Operation	CLK	LD#	R,W#	DQ			
WRITE cycle	L → H	L	L	Data in			
Load address, input write data on					Input data	D_A(A+0)	D_A(A+1)
consecutive K and K# rising edge					Input clock	K(t+1) ↑	K#(t+1) ↑
READ cycle	L → H	L	H	Data out			
Load address, read data on					Output data	Q_A(A+0)	Q_A(A+1)
consecutive K and K# rising edge					Output clock	K#(t+2) ↑	K(t+3) ↑
NOP (No operation)	L → H	H	X	DQ = High-Z			
Clock stop	Stopped	X	X	Previous state			

Remarks Remarks listed below are for both products with 2.0 and 2.5 Clock Cycles Read Latency.

1. H : HIGH, L : LOW, × : don't care, ↑ : rising edge.
2. Data inputs are registered at K and K# rising edges. Data outputs are delivered at K and K# rising edges.
3. All control inputs in the truth table must meet setup/hold times around the rising edge (LOW to HIGH) of K. All control inputs are registered during the rising edge of K.
4. This device contains circuitry that ensure the outputs to be in high impedance during power-up.
5. Refer to state diagram and timing diagrams for clarification.
6. A+0 refers to the address input during a WRITE or READ cycle.
   A+1 refers to the next internal burst address in accordance with the burst sequence.
7. It is recommended that K = K# when clock is stopped. This is not essential but permits most rapid restart by overcoming transmission line charging symmetrically.

Byte Write Operation

[μPD44646092A-A], [μPD44646093A-A]

Operation	K	K#	BW0#
Write DQ0 to DQ8	L → H	–	0
	–	L → H	0
Write nothing	L → H	–	1
	–	L → H	1

Remarks 1. H : HIGH, L : LOW, → : rising edge.

2. Assumes a WRITE cycle was initiated. BW0# can be altered for any portion of the BURST WRITE operation provided that the setup and hold requirements are satisfied.

[μPD44646182A-A], [μPD44646183A-A]

Operation	K	K#	BW0#	BW1#
Write DQ0 to DQ17	L → H	–	0	0
	–	L → H	0	0
Write DQ0 to DQ8	L → H	–	0	1
	–	L → H	0	1
Write DQ9 to DQ17	L → H	–	1	0
	–	L → H	1	0
Write nothing	L → H	–	1	1
	–	L → H	1	1

Remarks 1. H : HIGH, L : LOW, → : rising edge.

2. Assumes a WRITE cycle was initiated. BW0# and BW1# can be altered for any portion of the BURST WRITE operation provided that the setup and hold requirements are satisfied.

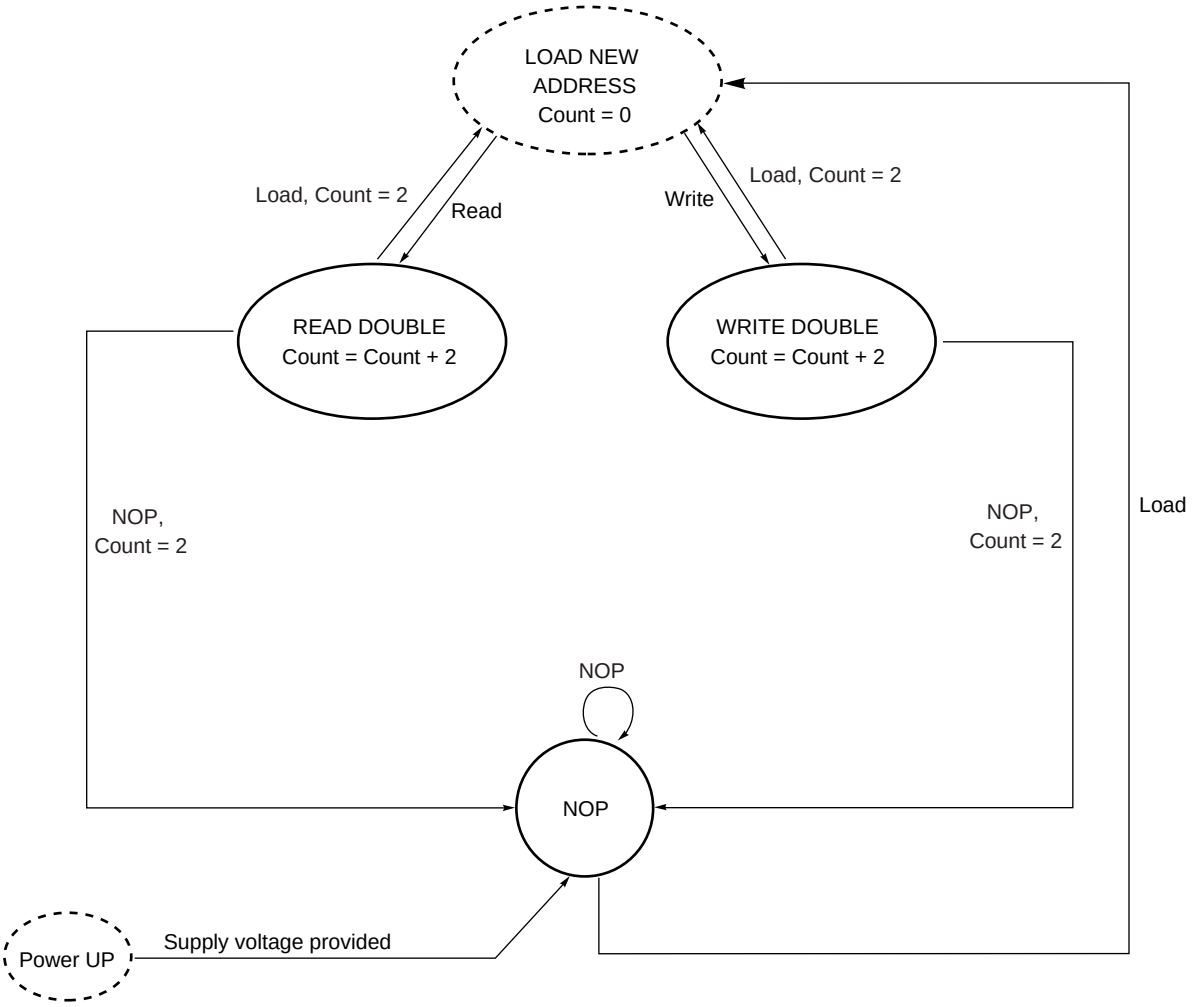
[μPD44646362A-A], [μPD44646363A-A]

Operation	K	K#	BW0#	BW1#	BW2#	BW3#
Write DQ0 to DQ35	L → H	–	0	0	0	0
	–	L → H	0	0	0	0
Write DQ0 to DQ8	L → H	–	0	1	1	1
	–	L → H	0	1	1	1
Write DQ9 to DQ17	L → H	–	1	0	1	1
	–	L → H	1	0	1	1
Write DQ18 to DQ26	L → H	–	1	1	0	1
	–	L → H	1	1	0	1
Write DQ27 to DQ35	L → H	–	1	1	1	0
	–	L → H	1	1	1	0
Write nothing	L → H	–	1	1	1	1
	–	L → H	1	1	1	1

Remarks 1. H : HIGH, L : LOW, → : rising edge.

2. Assumes a WRITE cycle was initiated. BW0# to BW3# can be altered for any portion of the BURST WRITE operation provided that the setup and hold requirements are satisfied.

Bus Cycle State Diagram



Remarks 1. Bus cycle is terminated after burst count = 2.

2. State machine control timing sequence is controlled by K.

Electrical Specifications

Absolute Maximum Ratings

Parameter	Symbol	Conditions	Rating	Unit
Supply voltage	V_{DD}		–0.5 to +2.5	V
Output supply voltage	V_{DDQ}		–0.5 to V_{DD}	V
Input voltage	V_{IN}		–0.5 to V_{DD} + 0.5 (2.5 V MAX.)	V
Input / Output voltage	$V_{I/O}$		–0.5 to V_{DDQ} + 0.5 (2.5 V MAX.)	V
Operating ambient temperature	T_A		0 to 70	°C
Storage temperature	T_{stg}		–55 to +125	°C

Caution Exposing the device to stress above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Recommended DC Operating Conditions (T_A = 0 to 70°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	Note
Supply voltage	V_{DD}		1.7	1.8	1.9	V	
Output supply voltage	V_{DDQ}		1.4		V_{DD}	V	1
Input HIGH voltage	$V_{IH (DC)}$		V_{REF} + 0.1		V_{DDQ} + 0.3	V	1, 2
Input LOW voltage	$V_{IL (DC)}$		–0.3		V_{REF} – 0.1	V	1, 2
Clock input voltage	V_{IN}		–0.3		V_{DDQ} + 0.3	V	1, 2
Reference voltage	V_{REF}		0.68		0.95	V	

Notes 1. During normal operation, V_{DDQ} must not exceed V_{DD}.

2. Power-up: $V_{IH} \leq V_{DDQ}$ + 0.3 V and $V_{DD} \leq$ 1.7 V and $V_{DDQ} \leq$ 1.4 V for t ≤ 200 ms

Recommended AC Operating Conditions (T_A = 0 to 70°C)

Parameter	Symbol	Conditions	MIN.	MAX.	Unit	Note
Input HIGH voltage	$V_{IH (AC)}$		V_{REF} + 0.2		V	1
Input LOW voltage	$V_{IL (AC)}$			V_{REF} – 0.2	V	1

Note 1. Overshoot: $V_{IH (AC)} \leq V_{DD}$ + 0.7 V (2.5 V MAX.) for t ≤ TKHKH/2

Undershoot: $V_{IL (AC)} \geq$ – 0.5 V for t ≤ TKHKH/2

Control input signals may not have pulse widths less than TKHKL (MIN.) or operate at cycle rates less than TKHKH (MIN.).

DC Characteristics (T_A = 0 to 70°C, V_{DD} = 1.8 ± 0.1 V)

Parameter	Symbol	Test condition		MIN.	MAX.			Unit	Note
					x9	x18	x36		
Input leakage current	I_{LI}			–2	+2			μA	4, 5
I/O leakage current	I_{LO}			–2	+2			μA	4
Operating supply current (Read cycle / Write cycle)	I_{DD}	$V_{IN} \le V_{IL}$ or $V_{IN} \ge V_{IH}$	-E20 Note1		690	740	850	mA	
		$I_{I/O}$ = 0 mA	-E22 Note1		650	695	790		
		Cycle = MAX.	-E25		610	650	730		
			-E30		530	590	670		
			-E33		490	560	640		
Standby supply current (NOP)	I_{SB1}	$V_{IN} \le V_{IL}$ or $V_{IN} \ge V_{IH}$	-E20 Note1		440	470	530	mA	
		$I_{I/O}$ = 0 mA	-E22 Note1		430	450	505		
		Cycle = MAX.	-E25		410	430	480		
		Inputs static	-E30		380	400	450		
			-E33		370	390	430		
Output HIGH voltage	$V_{OH(Low)}$	$\|I_{OH}\| \le 0.1$ mA		$V_{DD}Q$ – 0.2	$V_{DD}Q$			V	6, 7
	V_{OH}	**Note2**		$V_{DD}Q/2–0.12$	$V_{DD}Q/2+0.12$				6, 7
Output LOW voltage	$V_{OL(Low)}$	$I_{OL} \le 0.1$ mA		V_{SS}	0.2			V	6, 7
	V_{OL}	**Note3**		$V_{DD}Q/2–0.12$	$V_{DD}Q/2+0.12$				6, 7

Notes 1. -E20 and -E22 are valid for 2.5 Clock Cycles Read Latency products.

2. Outputs are impedance-controlled. $|I_{OH}| = (V_{DD}Q/2)/(RQ/5)$ ±15% for values of 175 Ω ≤ RQ ≤ 350 Ω.

3. Outputs are impedance-controlled. $I_{OL} = (V_{DD}Q/2)/(RQ/5)$ ±15% for values of 175 Ω ≤ RQ ≤ 350 Ω.

4. Measured with ODT off.

5. ODT pin is internally tied to V_{SS}, so input leakage current value is ±5 μA.

6. AC load current is higher than the shown DC values.

7. HSTL outputs meet JEDEC HSTL Class I standards.

Capacitance (T_A = 25°C, f = 1 MHz)

Parameter	Symbol	Test conditions	MIN.	MAX.	Unit
Input capacitance (Address, Control)	C_{IN}	V_{IN} = 0 V		4	pF
Input / Output capacitance (DQ, CQ, CQ#, QVLD)	$C_{I/O}$	$V_{I/O}$ = 0 V		5	pF
Clock Input capacitance	C_{clk}	V_{clk} = 0 V		4	pF

Remark These parameters are periodically sampled and not 100% tested.

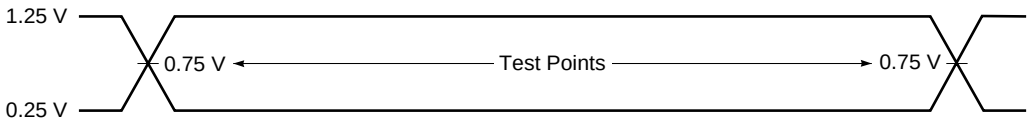
Thermal Characteristics

Parameter	Symbol	Substrate	Airflow	TYP.	Unit
Thermal resistance from junction to ambient air	θ_{ja}	4-layer	0 m/s	19.5	°C/W
			1 m/s	12.0	°C/W
		8-layer	0 m/s	18.1	°C/W
			1 m/s	11.3	°C/W
Thermal characterization parameter from junction to the top center of the package surface	Ψ_{jt}	4-layer	0 m/s	0.01	°C/W
			1 m/s	0.05	°C/W
		8-layer	0 m/s	0.01	°C/W
			1 m/s	0.04	°C/W
Thermal resistance from junction to case	θ_{jc}			2.14	°C/W

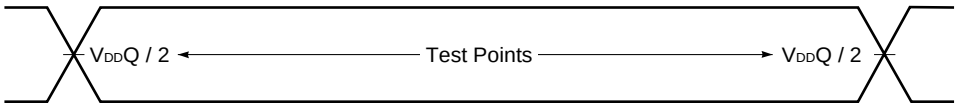
AC Characteristics (T_A = 0 to 70°C, V_{DD} = 1.8 ± 0.1 V)

AC Test Conditions (V_{DD} = 1.8 ± 0.1 V, $V_{DD}Q$ = 1.4 to V_{DD})

Input waveform (Rise / Fall time ≤ 0.3 ns)

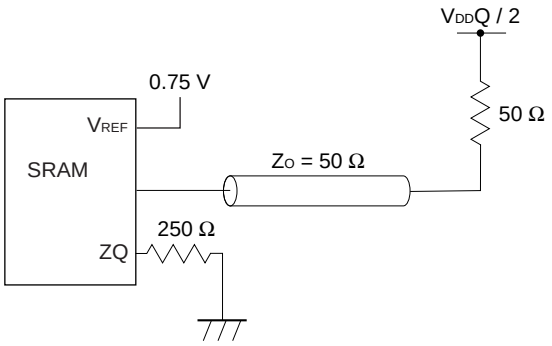


Output waveform



Output load condition

Figure 1. External load at test



Read and Write Cycle

Parameter	Symbol	-E20 Note1 (500 MHz)		-E22 Note1 (450 MHz)		-E25 (400 MHz)		-E30 (333 MHz)		-E33 (300 MHz)		Unit	Note
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Clock													
Average Clock cycle time (K, K#)	TKHKH	2.0	5.25	2.2	5.25	2.5	5.25	3.0	5.25	3.3	5.25	ns	2
Clock phase jitter (K, K#)	TKC var		0.15		0.15		0.20		0.20		0.20	ns	3
Clock HIGH time (K, K#)	TKHKL	0.4		0.4		0.4		0.4		0.4		TKHKH	
Clock LOW time (K, K#)	TKLKH	0.4		0.4		0.4		0.4		0.4		TKHKH	
Clock HIGH to Clock# HIGH (K → K#)	TKHK#H	0.85		0.95		1.06		1.28		1.40		ns	
Clock# HIGH to Clock HIGH (K# → K)	TK#HKH	0.85		0.95		1.06		1.28		1.40		ns	
DLL/PLL lock time (K)	TKC lock	20		20		20		20		20		μs	4
K static to DLL/PLL reset	TKC reset	30		30		30		30		30		ns	5
Output Times													
CQ HIGH to CQ# HIGH (CQ → CQ#)	TCQHCQ#H	0.6		0.7		0.81		1.03		1.15		ns	6
CQ# HIGH to CQ HIGH (CQ# → CQ)	TCQ#HCQH	0.6		0.7		0.81		1.03		1.15		ns	6
K, K# HIGH to output valid	TKHQV		0.45		0.45		0.45		0.45		0.45	ns	
K, K# HIGH to output hold	TKHQX	– 0.45		– 0.45		– 0.45		– 0.45		– 0.45		ns	
K, K# HIGH to echo clock valid	TKHCQV		0.45		0.45		0.45		0.45		0.45	ns	
K, K# HIGH to echo clock hold	TKHCQX	– 0.45		– 0.45		– 0.45		– 0.45		– 0.45		ns	
CQ, CQ# HIGH to output valid	TCQHQV		0.15		0.15		0.20		0.20		0.20	ns	7
CQ, CQ# HIGH to output hold	TCQHQX	– 0.15		– 0.15		– 0.20		– 0.20		– 0.20		ns	7
K HIGH to output High-Z	TKHQZ		0.45		0.45		0.45		0.45		0.45	ns	
K HIGH to output Low-Z	TKHQX1	– 0.45		– 0.45		– 0.45		– 0.45		– 0.45		ns	
CQ, CQ# HIGH to QVLD valid	TCQHQVLD	– 0.15	0.15	– 0.15	0.15	– 0.20	0.20	– 0.20	0.20	– 0.20	0.20	ns	
Setup Times													
Address valid to K rising edge	TAVKH	0.33		0.4		0.4		0.4		0.4		ns	8
Synchronous load input (LD#), read write input (R, W#) valid to K rising edge	TIVKH	0.33		0.4		0.4		0.4		0.4		ns	8
Data inputs and write data select inputs (BWx#) valid to K, K# rising edge	TDVKH	0.25		0.28		0.28		0.28		0.28		ns	8
Hold Times													
K rising edge to address hold	TKHAX	0.33		0.4		0.4		0.4		0.4		ns	8
K rising edge to synchronous load input (LD#), read write input (R, W#) hold	TKHIX	0.33		0.4		0.4		0.4		0.4		ns	8
K, K# rising edge to data inputs and write data select inputs (BWx#) hold	TKHDX	0.25		0.28		0.28		0.28		0.28		ns	8

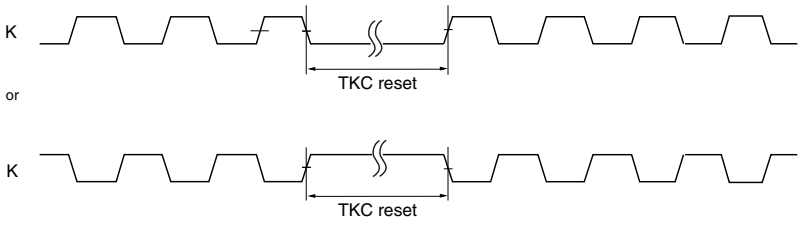
Notes 1. -E20 and –E22 are valid for 2.5 Clock Cycles Read Latency products.

2. When debugging the system or board, these products can operate at a clock frequency slower than TKHKH (MAX.) without the DLL/PLL circuit being used, if DLL# = LOW. Read latency (RL) is changed to 1.0 clock cycle regardless of RL = 2.0 and 2.5 clock cycles products in this operation. The AC/DC characteristics cannot be guaranteed, however.

3. Clock phase jitter is the variance from clock rising edge to the next expected clock rising edge. TKC var (MAX.) indicates a peak-to-peak value.

4. V_{DD} slew rate must be less than 0.1 V DC per 50 ns for DLL/PLL lock retention.
DLL/PLL lock time begins once V_{DD} and input clock are stable.
It is recommended that the device is kept NOP (LD# = HIGH) during these cycles.

5. K input is monitored for this operation. See below for the timing.



6. Guaranteed by design.

7. Echo clock is very tightly controlled to data valid / data hold. By design, there is a ± 0.1 ns variation from echo clock to data. The data sheet parameters reflect tester guardbands and test setup variations.

8. This is a synchronous device. All addresses, data and control lines must meet the specified setup and hold times for all latching clock edges.

Remarks 1. This parameter is sampled.

2. Test conditions as specified with the output loading as shown in AC Test Conditions unless otherwise noted.

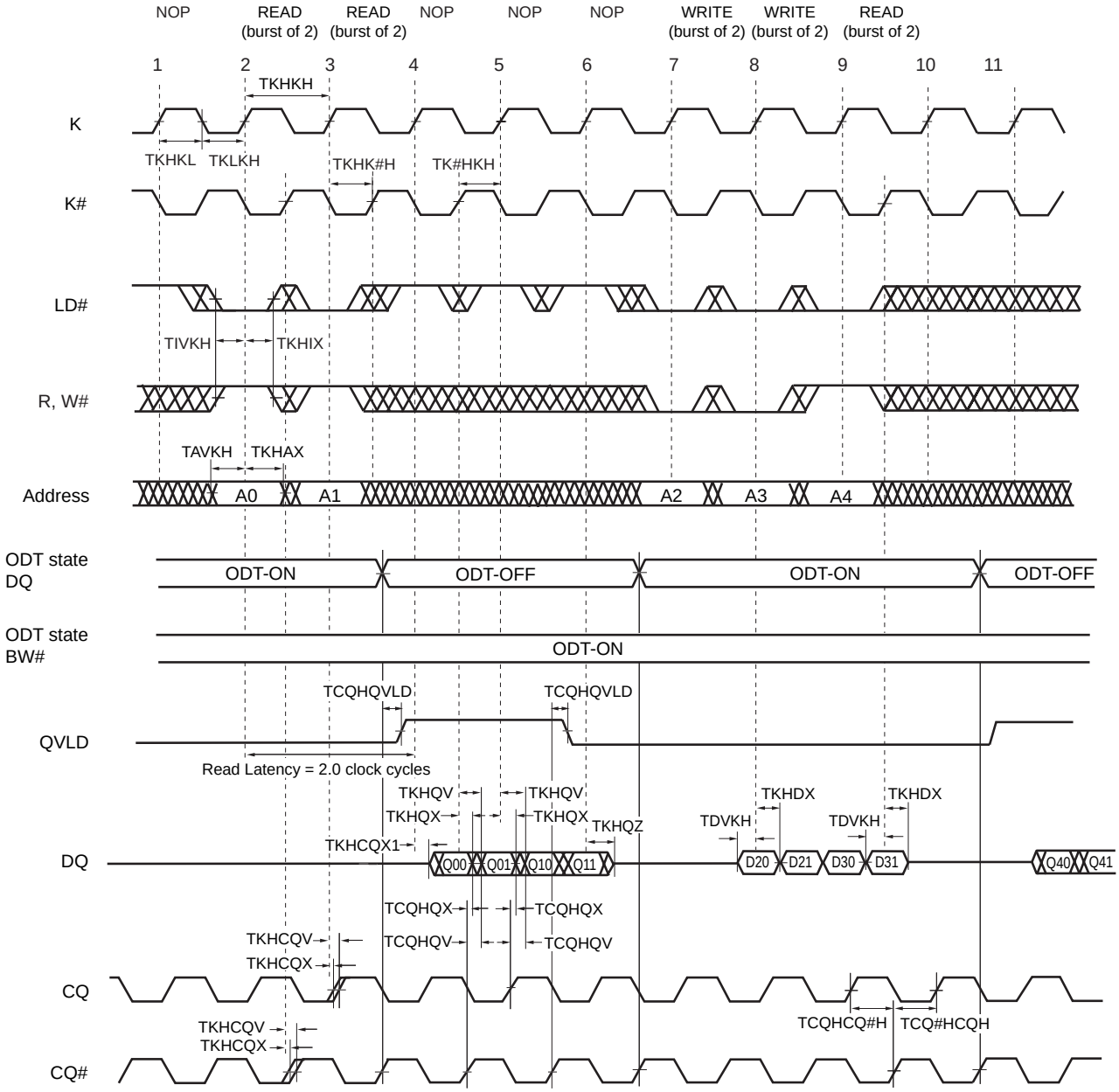
3. Control input signals may not be operated with pulse widths less than TKHKL (MIN.).

4. $V_{DD}Q$ is 1.5 V DC.

Read and Write Timing

2.0 Clock Cycles Read Latency

[μPD44646092A-A], [μPD44646182A-A], [μPD44646362A-A]



Remarks 1. Q00 refers to output from address A0.
Q01 refers to output from the next internal burst address following A0, etc.

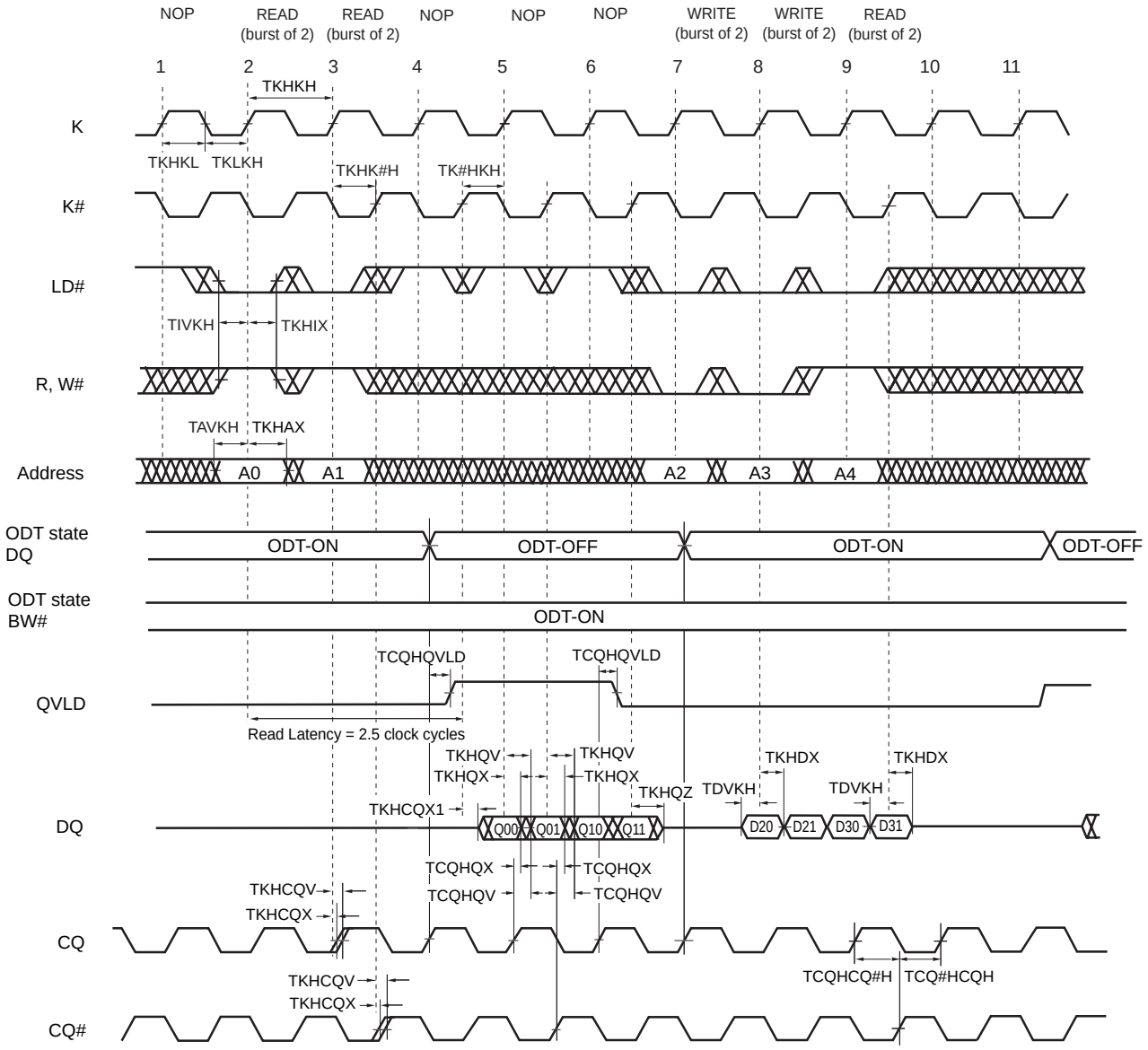
2. Outputs are disabled (high impedance) 3 clock cycles after the last READ (LD# = LOW, R, W# = HIGH) is input in the sequences of [READ]-[NOP].

3. The third NOP cycle between Read to Write transition may not be necessary for correct device operation when Read latency = 2.0 clock cycles. However, it may be required to avoid bus contention.

4. When the ODT control pin is LOW or No Connect, the ODT function is always off.

2.5 Clock Cycles Read Latency

[μPD44646093A-A], [μPD44646183A-A], [μPD44646363A-A]

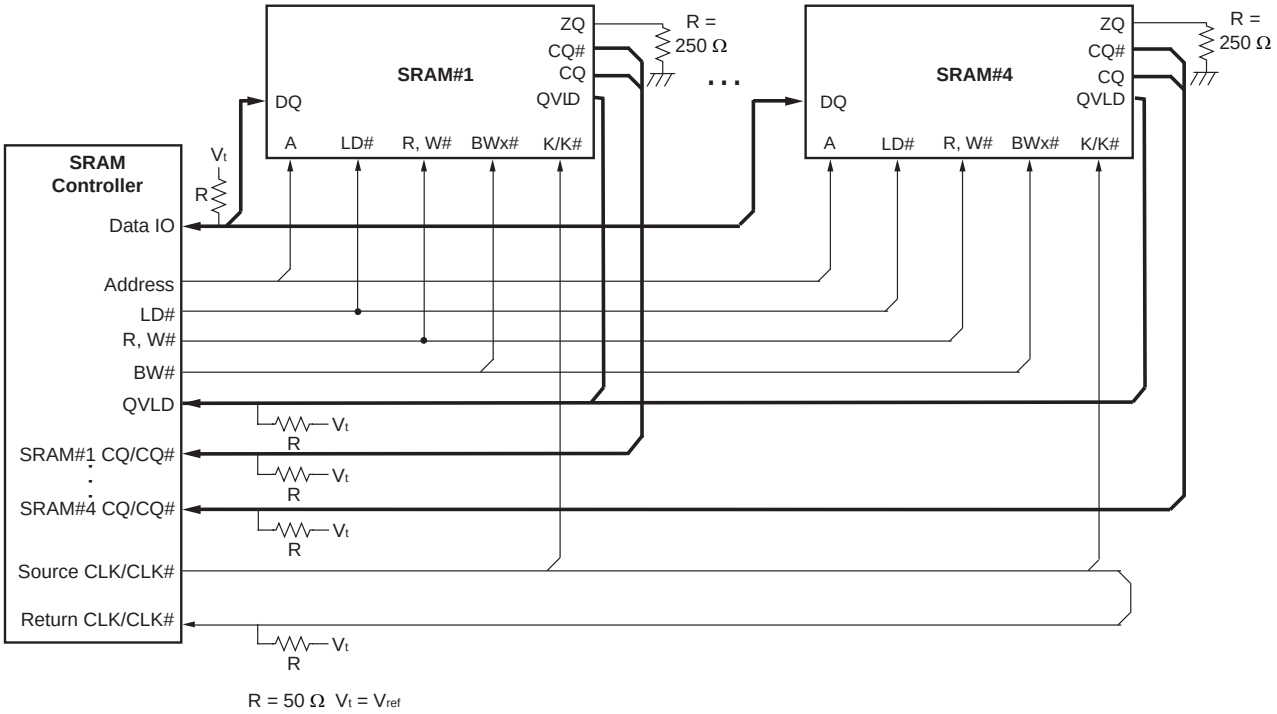


Remarks 1. Q00 refers to output from address A0.
Q01 refers to output from the next internal burst address following A0, etc.

2. Outputs are disabled (high impedance) 3.5 clock cycles after the last READ (LD# = LOW, R, W# = HIGH) is input in the sequences of [READ]-[NOP].

3. When the ODT control pin is LOW or No Connect, the ODT function is always off.

Application Example



Remark AC specifications are defined at the condition of SRAM outputs, CQ, CQ#, QVLD and DQ with termination. DQs and BW#s have ODT.

JTAG Specification

These products support a limited set of JTAG functions as in IEEE standard 1149.1.

Test Access Port (TAP) Pins

Pin name	Pin assignments	Description
TCK	2R	Test Clock Input. All input are captured on the rising edge of TCK and all outputs propagate from the falling edge of TCK.
TMS	10R	Test Mode Select. This is the command input for the TAP controller state machine.
TDI	11R	Test Data Input. This is the input side of the serial registers placed between TDI and TDO. The register placed between TDI and TDO is determined by the state of the TAP controller state machine and the instruction that is currently loaded in the TAP instruction.
TDO	1R	Test Data Output. This is the output side of the serial registers placed between TDI and TDO. Output changes in response to the falling edge of TCK.

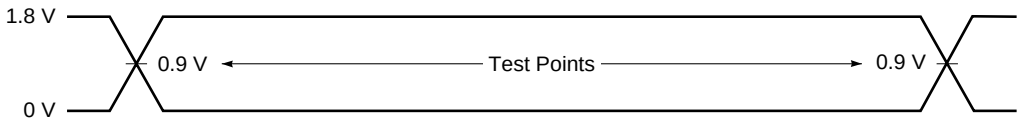
Remark The device does not have TRST (TAP reset). The Test-Logic Reset state is entered while TMS is held HIGH for five rising edges of TCK. The TAP controller state is also reset on the SRAM POWER-UP.

JTAG DC Characteristics (T_A = 0 to 70°C, V_{DD} = 1.8 ± 0.1 V, unless otherwise noted)

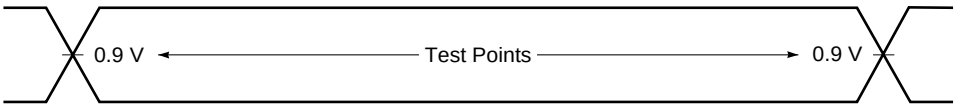
Parameter	Symbol	Conditions	MIN.	MAX.	Unit
JTAG Input leakage current	I_{LI}	0 V ≤ V_{IN} ≤ V_{DD}	–5.0	+5.0	μA
JTAG I/O leakage current	I_{LO}	0 V ≤ V_{IN} ≤ V_{DD}Q, Outputs disabled	–5.0	+5.0	μA
JTAG input HIGH voltage	V_{IH}		1.3	V_{DD}+0.3	V
JTAG input LOW voltage	V_{IL}		–0.3	+0.5	V
JTAG output HIGH voltage	V_{OH1}	| I_{OHC} | = 100 μA	1.6		V
	V_{OH2}	| I_{OHT} | = 2 mA	1.4		V
JTAG output LOW voltage	V_{OL1}	I_{OLC} = 100 μA		0.2	V
	V_{OL2}	I_{OLT} = 2 mA		0.4	V

JTAG AC Test Conditions

Input waveform (Rise / Fall time ≤ 1 ns)

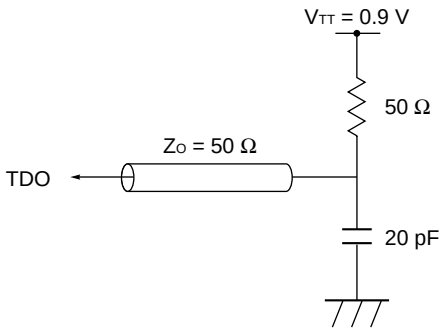


Output waveform



Output load

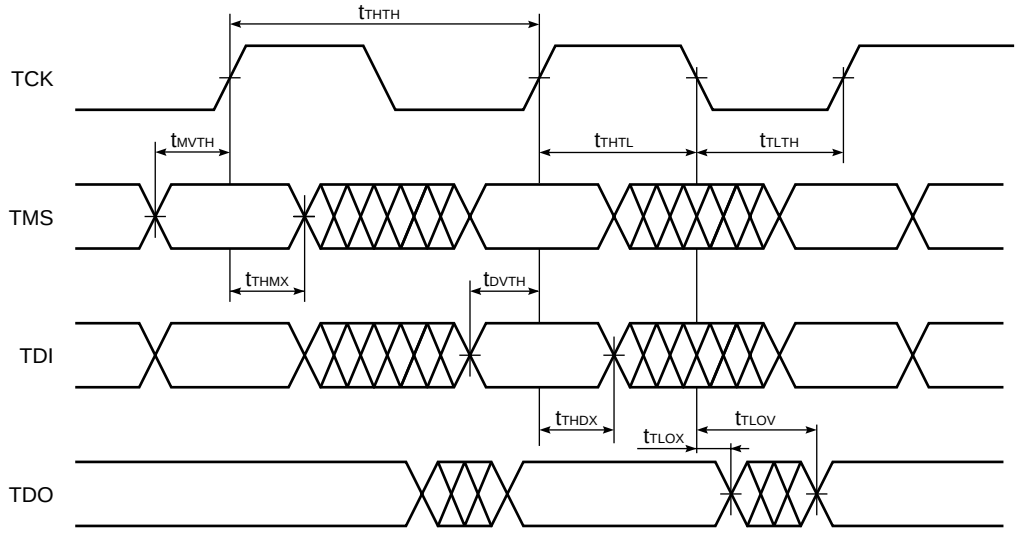
Figure 2. External load at test



JTAG AC Characteristics (T_A = 0 to 70°C)

Parameter	Symbol	Conditions	MIN.	MAX.	Unit
Clock					
Clock cycle time	t_{THTH}		50		ns
Clock frequency	f_{TF}			20	MHz
Clock HIGH time	t_{THTL}		20		ns
Clock LOW time	t_{TLTH}		20		ns
Output time					
TCK LOW to TDO unknown	t_{TLOX}		0		ns
TCK LOW to TDO valid	t_{TLOV}			10	ns
Setup time					
TMS setup time	t_{MVTH}		5		ns
TDI valid to TCK HIGH	t_{DVTH}		5		ns
Capture setup time	t_{CS}		5		ns
Hold time					
TMS hold time	t_{THMX}		5		ns
TCK HIGH to TDI invalid	t_{THDX}		5		ns
Capture hold time	t_{CH}		5		ns

JTAG Timing Diagram



Scan Register Definition (1)

Register name	Description
Instruction register	The instruction register holds the instructions that are executed by the TAP controller when it is moved into the run-test/idle or the various data register state. The register can be loaded when it is placed between the TDI and TDO pins. The instruction register is automatically preloaded with the IDCODE instruction at power-up whenever the controller is placed in test-logic-reset state.
Bypass register	The bypass register is a single bit register that can be placed between TDI and TDO. It allows serial test data to be passed through the RAMs TAP to another device in the scan chain with as little delay as possible.
ID register	The ID Register is a 32 bit register that is loaded with a device and vendor specific 32 bit code when the controller is put in capture-DR state with the IDCODE command loaded in the instruction register. The register is then placed between the TDI and TDO pins when the controller is moved into shift-DR state.
Boundary register	The boundary register, under the control of the TAP controller, is loaded with the contents of the RAMs I/O ring when the controller is in capture-DR state and then is placed between the TDI and TDO pins when the controller is moved to shift-DR state. Several TAP instructions can be used to activate the boundary register. The Scan Exit Order tables describe which device bump connects to each boundary register location. The first column defines the bit's position in the boundary register. The second column is the name of the input or I/O at the bump and the third column is the bump number.

Scan Register Definition (2)

Register name	Bit size	Unit
Instruction register	3	bit
Bypass register	1	bit
ID register	32	bit
Boundary register	109	bit

ID Register Definition

2.0 Clock Cycles Read Latency

Part number	Organization	ID [31:28] vendor revision no.	ID [27:12] part no.	ID [11:1] vendor ID no.	ID [0] fix bit
μPD44646092A-A	8M x 9	XXXX	0000 0000 1000 1100	00000010000	1
μPD44646182A-A	4M x 18	XXXX	0000 0000 1000 1101	00000010000	1
μPD44646362A-A	2M x 36	XXXX	0000 0000 1000 1110	00000010000	1

2.5 Clock Cycles Read Latency

Part number	Organization	ID [31:28] vendor revision no.	ID [27:12] part no.	ID [11:1] vendor ID no.	ID [0] fix bit
μPD44646093A-A	8M x 9	XXXX	0000 0000 1001 1000	00000010000	1
μPD44646183A-A	4M x 18	XXXX	0000 0000 1001 1001	00000010000	1
μPD44646363A-A	2M x 36	XXXX	0000 0000 1001 1010	00000010000	1

SCAN Exit Order

Bit no.	Signal name x9	x18	x36	Bump ID
1	ODT			6R
2	QVLD			6P
3	A			6N
4	A			7P
5	A			7N
6	A			7R
7	A			8R
8	A			8P
9	A			9R
10	DQ0			11P
11	NC	NC	DQ9	10P
12	NC			10N
13	NC			9P
14	NC	DQ1	DQ11	10M
15	NC	NC	DQ10	11N
16	NC			9M
17	NC			9N
18	DQ1	DQ2	DQ2	11L
19	NC	NC	DQ1	11M
20	NC			9L
21	NC			10L
22	NC	DQ3	DQ3	11K
23	NC	NC	DQ12	10K
24	NC			9J
25	NC			9K
26	DQ2	DQ4	DQ13	10J
27	NC	NC	DQ4	11J
28	ZQ			11H
29	NC			10G
30	NC			9G
31	NC	DQ5	DQ5	11F
32	NC	NC	DQ14	11G
33	NC			9F
34	NC			10F
35	DQ3	DQ6	DQ6	11E
36	NC	NC	DQ15	10E

Bit no.	Signal name x9	x18	x36	Bump ID
37	NC			10D
38	NC			9E
39	NC	DQ7	DQ17	10C
40	NC	NC	DQ16	11D
41	NC			9C
42	NC			9D
43	DQ4	DQ8	DQ8	11B
44	NC	NC	DQ7	11C
45	NC			9B
46	NC			10B
47	CQ			11A
48	A			10A
49	A			9A
50	A			8B
51	A			7C
52	A	NC	NC	6C
53	LD#			8A
54	NC	NC	BW1#	7A
55	BW0#			7B
56	K			6B
57	K#			6A
58	NC	NC	BW3#	5B
59	NC	BW1#	BW2#	5A
60	R, W#			4A
61	A			5C
62	A			4B
63	A			3A
64	A	A	NC	2A
65	CQ#			1A
66	NC	DQ9	DQ27	2B
67	NC	NC	DQ18	3B
68	NC			1C
69	NC			1B
70	NC	DQ10	DQ19	3D
71	NC	NC	DQ28	3C
72	NC			1D

Bit no.	Signal name x9	x18	x36	Bump ID
73	NC			2C
74	DQ5	DQ11	DQ20	3E
75	NC	NC	DQ29	2D
76	NC			2E
77	NC			1E
78	NC	DQ12	DQ30	2F
79	NC	NC	DQ21	3F
80	NC			1G
81	NC			1F
82	DQ6	DQ13	DQ22	3G
83	NC	NC	DQ31	2G
84	DLL#			1H
85	NC			1J
86	NC			2J
87	NC	DQ14	DQ23	3K
88	NC	NC	DQ32	3J
89	NC			2K
90	NC			1K
91	DQ7	DQ15	DQ33	2L
92	NC	NC	DQ24	3L
93	NC			1M
94	NC			1L
95	NC	DQ16	DQ25	3N
96	NC	NC	DQ34	3M
97	NC			1N
98	NC			2M
99	DQ8	DQ17	DQ26	3P
100	NC	NC	DQ35	2N
101	NC			2P
102	NC			1P
103	A			3R
104	A			4R
105	A			4P
106	A			5P
107	A			5N
108	A			5R
109	–			Internal

JTAG Instructions

Instructions	Description
EXTEST	The EXTEST instruction allows circuitry external to the component package to be tested. Boundary-scan register cells at output pins are used to apply test vectors, while those at input pins capture test results. Typically, the first test vector to be applied using the EXTEST instruction will be shifted into the boundary scan register using the PRELOAD instruction. Thus, during the update-IR state of EXTEST, the output drive is turned on and the PRELOAD data is driven onto the output pins.
IDCODE	The IDCODE instruction causes the ID ROM to be loaded into the ID register when the controller is in capture-DR mode and places the ID register between the TDI and TDO pins in shift-DR mode. The IDCODE instruction is the default instruction loaded in at power up and any time the controller is placed in the test-logic-reset state.
BYPASS	When the BYPASS instruction is loaded in the instruction register, the bypass register is placed between TDI and TDO. This occurs when the TAP controller is moved to the shift-DR state. This allows the board level scan path to be shortened to facilitate testing of other devices in the scan path.
SAMPLE / PRELOAD	SAMPLE / PRELOAD is a Standard 1149.1 mandatory public instruction. When the SAMPLE / PRELOAD instruction is loaded in the instruction register, moving the TAP controller into the capture-DR state loads the data in the RAMs input and DQ pins into the boundary scan register. Because the RAM clock(s) are independent from the TAP clock (TCK) it is possible for the TAP to attempt to capture the I/O ring contents while the input buffers are in transition (i.e., in a metastable state). Although allowing the TAP to sample metastable input will not harm the device, repeatable results cannot be expected. RAM input signals must be stabilized for long enough to meet the TAPs input data capture setup plus hold time (t_{CS} plus t_{CH}). The RAMs clock inputs need not be paused for any other TAP operation except capturing the I/O ring contents into the boundary scan register. Moving the controller to shift-DR state then places the boundary scan register between the TDI and TDO pins.
SAMPLE-Z	If the SAMPLE-Z instruction is loaded in the instruction register, all RAM DQ pins are forced to an inactive drive state (high impedance) and the boundary register is connected between TDI and TDO when the TAP controller is moved to the shift-DR state.

JTAG Instruction Coding

IR2	IR1	IR0	Instruction	Note
0	0	0	EXTEST	
0	0	1	IDCODE	
0	1	0	SAMPLE-Z	1
0	1	1	RESERVED	2
1	0	0	SAMPLE / PRELOAD	
1	0	1	RESERVED	2
1	1	0	RESERVED	2
1	1	1	BYPASS	

Notes 1. TRISTATE all DQ pins and CAPTURE the pad values into a SERIAL SCAN LATCH.

2. Do not use this instruction code because the vendor uses it to evaluate this product.

Output Pin States of CQ, CQ#, QVLD and DQ

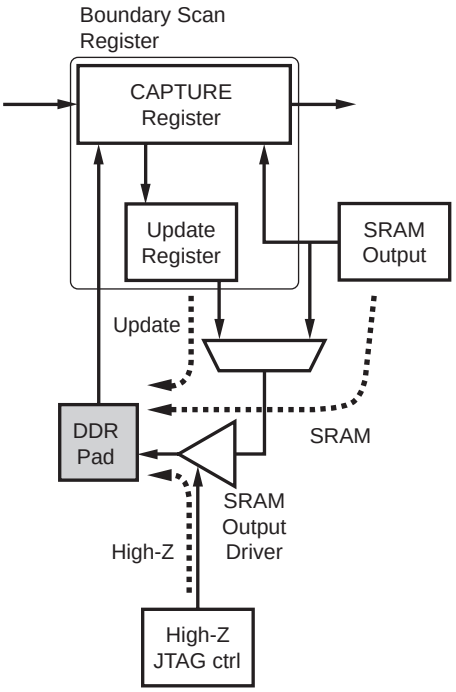
Instructions	Control-Register Status	Output Pin Status	
		CQ, CQ#, QVLD	DQ
EXTEST	0	Update	High-Z
	1	Update	Update
IDCODE	0	SRAM	SRAM
	1	SRAM	SRAM
SAMPLE-Z	0	High-Z	High-Z
	1	High-Z	High-Z
SAMPLE	0	SRAM	SRAM
	1	SRAM	SRAM
BYPASS	0	SRAM	SRAM
	1	SRAM	SRAM

Remark The output pin statuses during each instruction vary according to the Control-Register status (value of Boundary Scan Register, bit no. 109).
There are three statuses:

Update : Contents of the “Update Register” are output to the output pin (DDR Pad).
SRAM : Contents of the SRAM internal output “SRAM Output” are output to the output pin (DDR Pad).
High-Z : The output pin (DDR Pad) becomes high impedance by controlling of the “High-Z JTAG ctrl”.

The Control-Register status is set during Update-DR at the EXTEST or SAMPLE instruction.

In case checking the QVLD output status in EXTEST mode, please make sure stay DLL# pin HIGH.



Boundary Scan Register Status of Output Pins CQ, CQ#, QVLD and DQ

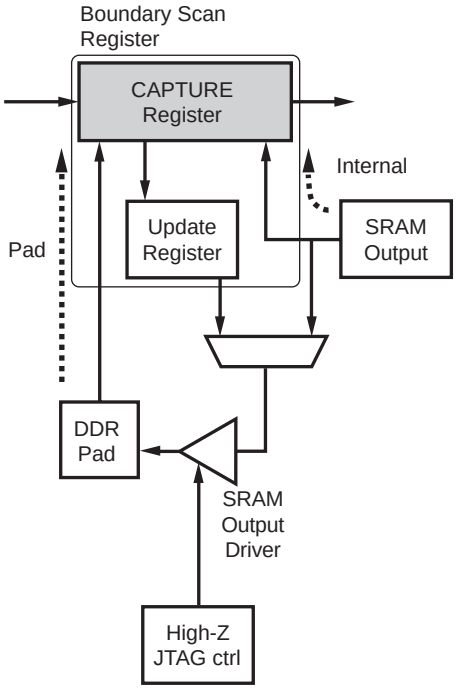
Instructions	SRAM Status	Boundary Scan Register Status		Note
		CQ, CQ#, QVLD	DQ	
EXTEST	READ (Low-Z)	Pad	Pad	
	NOP (High-Z)	Pad	Pad	
IDCODE	READ (Low-Z)	–	–	No definition
	NOP (High-Z)	–	–	
SAMPLE-Z	READ (Low-Z)	Pad	Pad	
	NOP (High-Z)	Pad	Pad	
SAMPLE	READ (Low-Z)	Internal	Internal	
	NOP (High-Z)	Internal	Pad	
BYPASS	READ (Low-Z)	–	–	No definition
	NOP (High-Z)	–	–	

Remark The Boundary Scan Register statuses during execution each instruction vary according to the instruction code and SRAM operation mode.

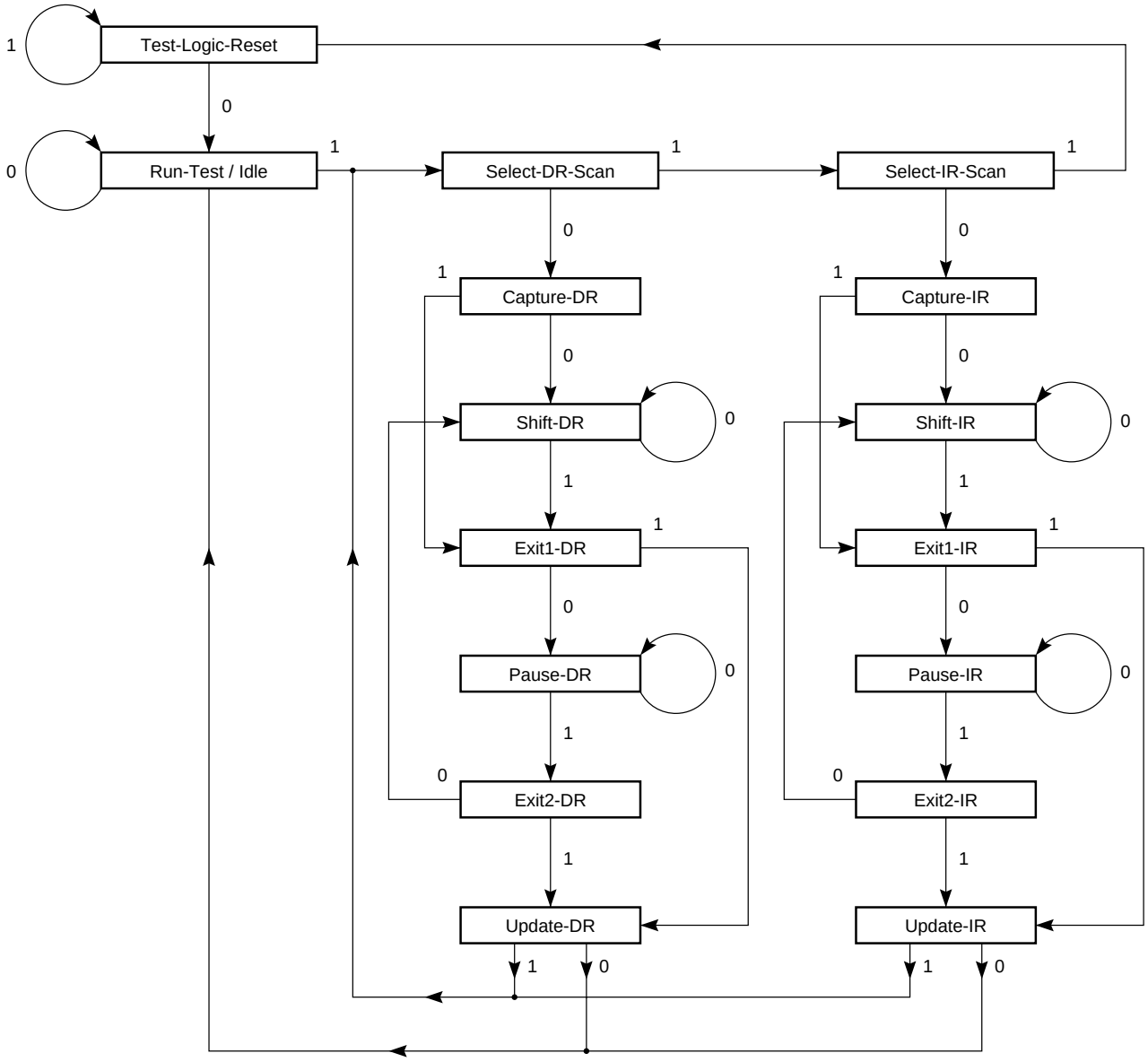
There are two statuses:

Pad : Contents of the output pin (DDR Pad) are captured in the “CAPTURE Register” in the Boundary Scan Register.

Internal : Contents of the SRAM internal output “SRAM Output” are captured in the “CAPTURE Register” in the Boundary Scan Register.



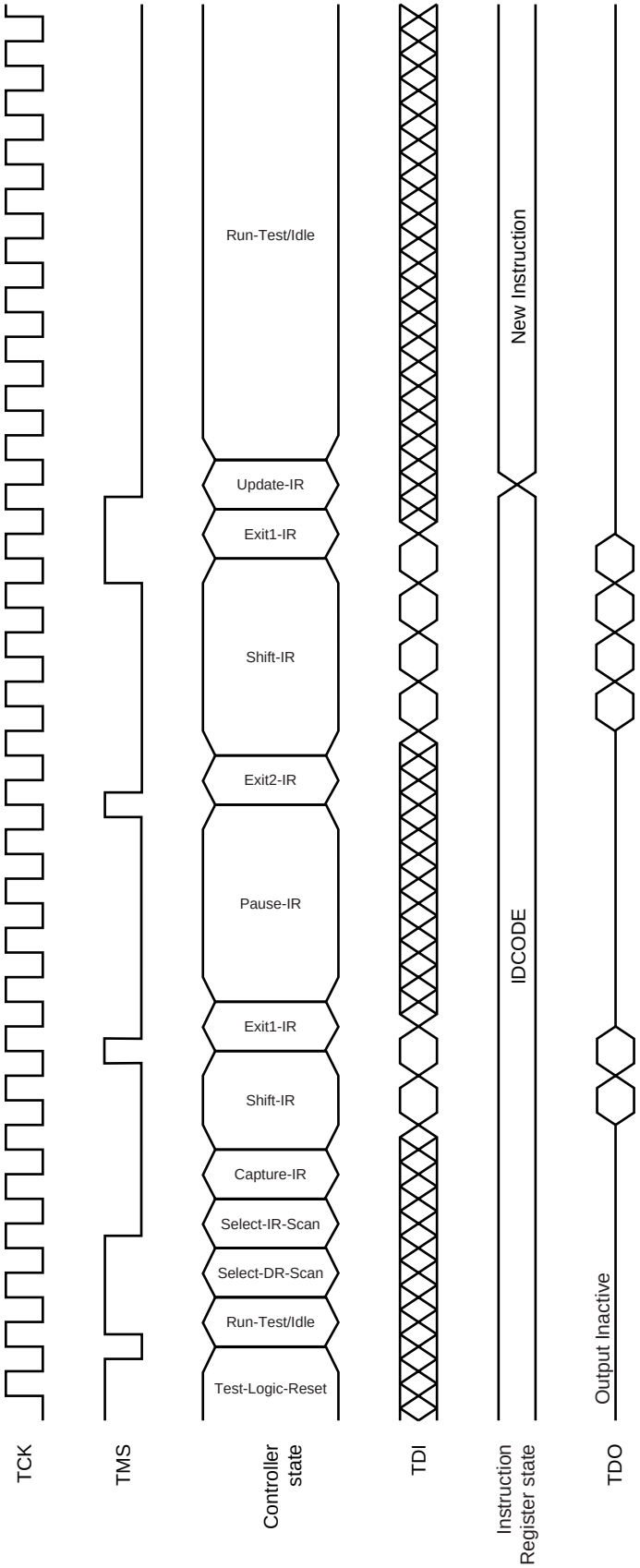
TAP Controller State Diagram



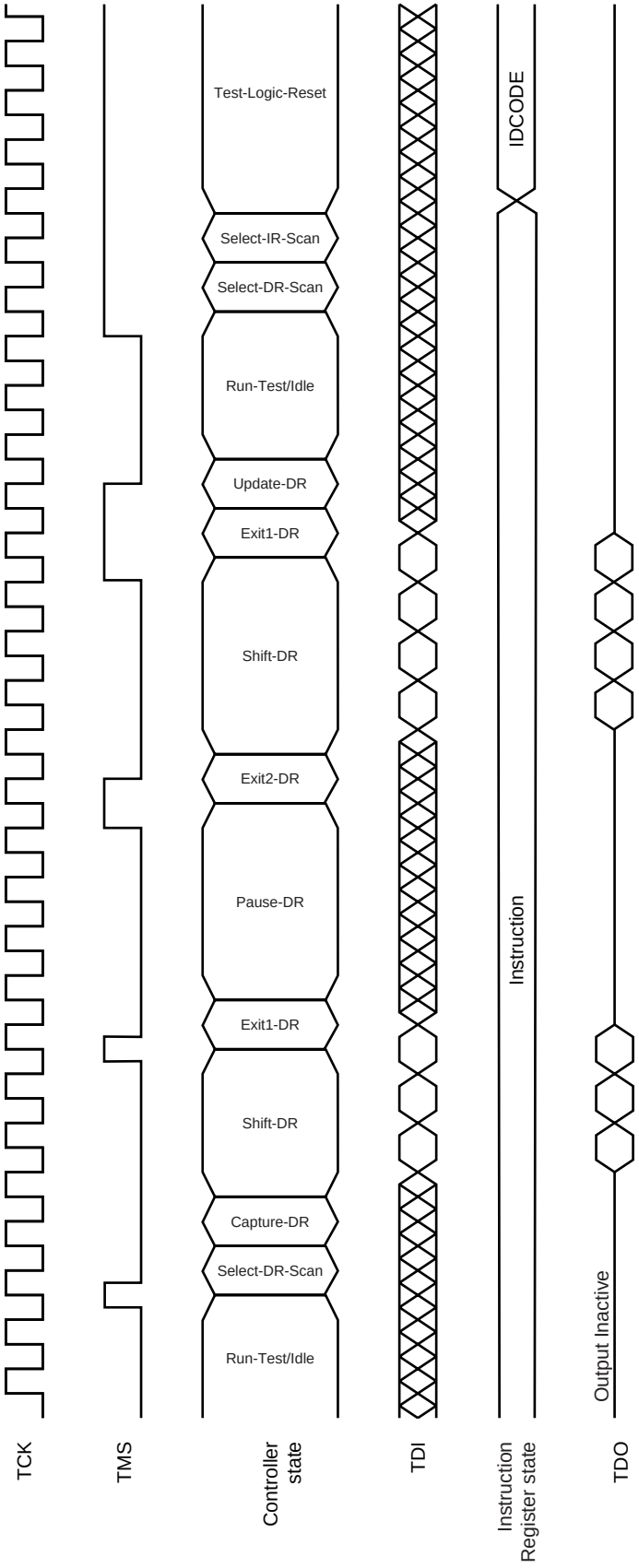
Disabling the Test Access Port

It is possible to use this device without utilizing the TAP. To disable the TAP Controller without interfering with normal operation of the device, TCK must be tied to V_{SS} to preclude mid level inputs. TDI and TMS may be left open but fix them to V_{DD} via a resistor of about 1 kΩ when the TAP controller is not used. TDO should be left unconnected also when the TAP controller is not used.

Test Logic Operation (Instruction Scan)

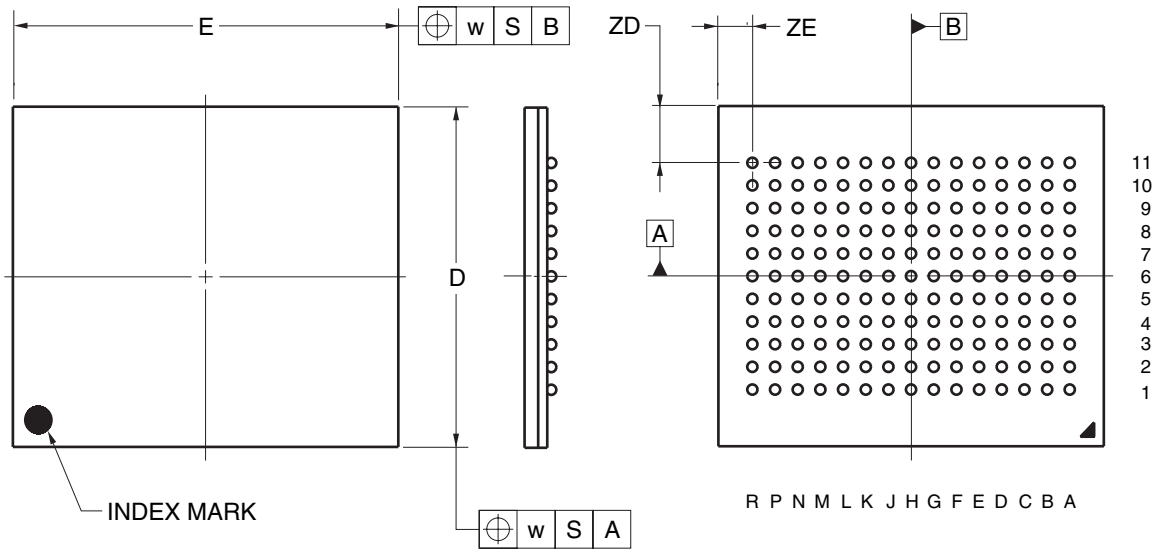


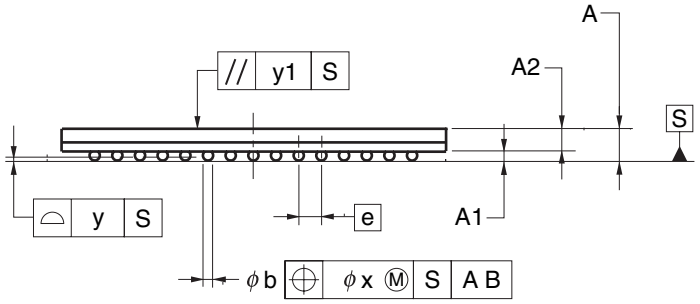
Test Logic (Data Scan)



Package Drawing

165-PIN PLASTIC BGA(15x17)





(UNIT:mm)

ITEM	DIMENSIONS
D	15.00±0.10
E	17.00±0.10
w	0.30
A	1.35±0.11
A1	0.37±0.05
A2	0.98
e	1.00
b	$0.50^{+0.10}_{-0.05}$
x	0.10
y	0.15
y1	0.25
ZD	2.50
ZE	1.50

P165F5-100-FQ1-1

Recommended Soldering Condition

Please consult with our sales offices for soldering conditions of these products.

Types of Surface Mount Devices

μPD44646092AF5-FQ1-A : 165-pin PLASTIC BGA (15 x 17), Lead free
μPD44646182AF5-FQ1-A : 165-pin PLASTIC BGA (15 x 17), Lead free
μPD44646362AF5-FQ1-A : 165-pin PLASTIC BGA (15 x 17), Lead free
μPD44646093AF5-FQ1-A : 165-pin PLASTIC BGA (15 x 17), Lead free
μPD44646183AF5-FQ1-A : 165-pin PLASTIC BGA (15 x 17), Lead free
μPD44646363AF5-FQ1-A : 165-pin PLASTIC BGA (15 x 17), Lead free

Related Document

Document Name	Document Number
μPD44646092A, 44646182A, 44646362A, 44646093A, 44646183A, 44646363A Data Sheet (Leaded products)	M19060

Quality Grade

- A quality grade of the products is “Standard”.
- Anti-radioactive design is not implemented in the products.
- Semiconductor devices have the possibility of unexpected defects by affection of cosmic ray that reach to the ground and so forth.

Revision History

Edition/ Date	Page		Type of revision	Location	Description (Previous edition → This edition)
	This edition	Previous edition			
2nd edition/ Mar. 2010	Throughout	Throughout	Modification		Preliminary Data Sheet → Data Sheet

[MEMO]

[MEMO]

NOTES FOR CMOS DEVICES

① VOLTAGE APPLICATION WAVEFORM AT INPUT PIN

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (MAX) and V_{IH} (MIN) due to noise, etc., the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (MAX) and V_{IH} (MIN).

② HANDLING OF UNUSED INPUT PINS

Unconnected CMOS device inputs can be cause of malfunction. If an input pin is unconnected, it is possible that an internal input level may be generated due to noise, etc., causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND via a resistor if there is a possibility that it will be an output pin. All handling related to unused pins must be judged separately for each device and according to related specifications governing the device.

③ PRECAUTION AGAINST ESD

A strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it when it has occurred. Environmental control must be adequate. When it is dry, a humidifier should be used. It is recommended to avoid using insulators that easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors should be grounded. The operator should be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with mounted semiconductor devices.

④ STATUS BEFORE INITIALIZATION

Power-on does not necessarily define the initial status of a MOS device. Immediately after the power source is turned ON, devices with reset functions have not yet been initialized. Hence, power-on does not guarantee output pin levels, I/O settings or contents of registers. A device is not initialized until the reset signal is received. A reset operation must be executed immediately after power-on for devices with reset functions.

⑤ POWER ON/OFF SEQUENCE

In the case of a device that uses different power supplies for the internal operation and external interface, as a rule, switch on the external power supply after switching on the internal power supply. When switching the power supply off, as a rule, switch off the external power supply and then the internal power supply. Use of the reverse power on/off sequences may result in the application of an overvoltage to the internal elements of the device, causing malfunction and degradation of internal elements due to the passage of an abnormal current.

The correct power on/off sequence must be judged separately for each device and according to related specifications governing the device.

⑥ INPUT OF SIGNAL DURING POWER OFF STATE

Do not input signals or an I/O pull-up power supply while the device is not powered. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements.

Input of signals during the power off state must be judged separately for each device and according to related specifications governing the device.

QDR RAMs and Quad Data Rate RAMs comprise a new series of products developed by Cypress Semiconductor, Renesas, IDT, NEC Electronics, and Samsung.

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  "Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support).

  "Specific": Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems and medical equipment for life support, etc.

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